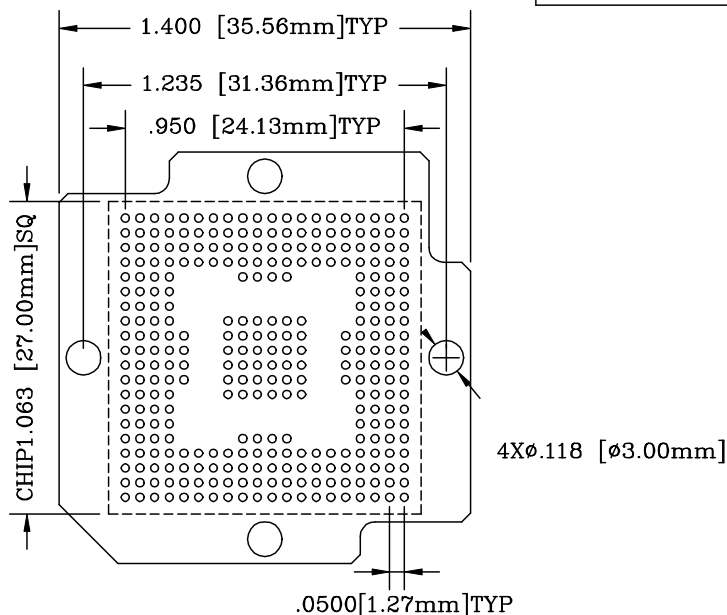
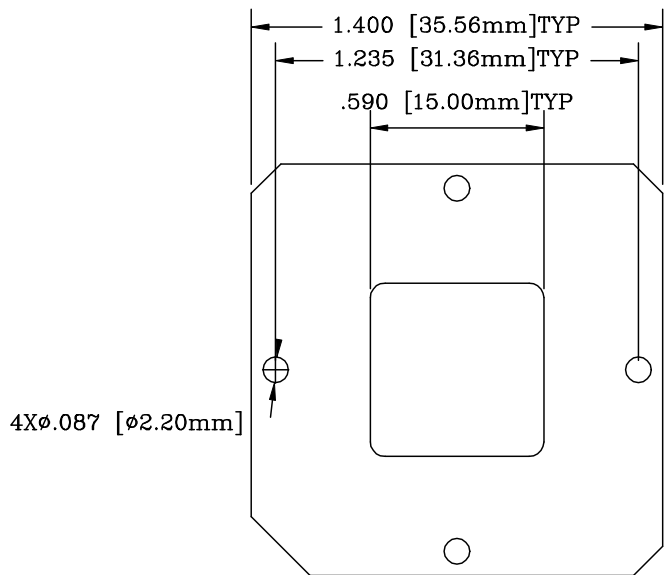


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	03/16/01	H.N.

SKT1191
DOD 41191

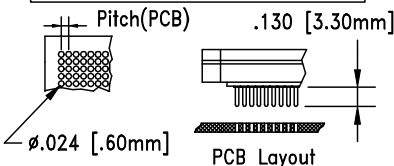
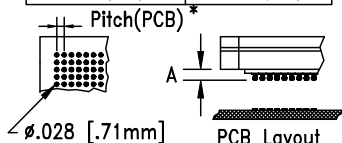


RETENTION FRAME SCALE 2:1 SOCKET

RECOMMENDED PAD LAYOUT

SOLDERTAIL STYLE	
REGULAR SMT STYLE XX = (-SM) YY = (-30)	RAISED SMT STYLE XX = (-RC) YY = (-29)

SOLDERTAIL = THRU HOLE STYLE
XX = (-ET) YY = (-70)



30= standard SMD ("A" = .047 [1.20mm])
29= raised SMD ("A" = .197 [5.00mm])

BALL DIAMETER FOR:
-29(RC) = .026 [0.66mm]
-30(SM) = .026 [0.66mm]

PIN DIAMETER FOR:
-70(ET) = .018 [0.45mm]

* The pitch dimension depends on your Ball Grid Array Package

PACKAGE SPECIFICATIONS

PIN COUNT	= 308
LEAD PITCH	= 1.27mm
GRID SIZE	= 20X20
PACKAGE SIZE	= 27.00mm

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.

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SHEET: 1 OF 1	DATE: 03/16/01	REVISION: A	ASSEMBLY DRAWING
CHECKED: Perry Munroe	DRAWN: Huy Nguyen	ITEM: S-BGA-20-308-XX	
DO NOT SCALE DRAWING			DESCRIPTION: BPW-308-2BG020-YY